

Atal Incubation Centre-Pondicherry
Engineering College Foundation
(AIC-PECF)



Tender Document

(For Design, Development and Supply of Customized Development Boards for
Electronic Design & Fab LAB at AIC-PECF as a single Package)

(Tender Reference Number : Proc/AIC-PECF/ 2020/036)

Date of Tender : 01-09-2020

www.aicpecf.org

(Contains 58 Pages Numbered Serially including this cover Sheet)

NOTICE INVITING TENDER

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Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF) supported by Atal Innovation Mission, NITI Aayog, Government of India for promotion of innovation and startups. To set up the electronic design and manufacturing (EDM) and Fab Lab in AIC-PECF, sealed tenders are invited (Technical & Commercial bid in two separate envelopes) under two bid system for design, development and supply of customized Development boards for Electronic Design & Fab LAB at AIC-PECF as a single package, from eligible suppliers.

The details are summarized below:-

1	Tender number	Proc/AIC-PECF/ 2020/036
2	Purchaser	Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), PEC Campus, Pillaichavady, Puducherry-605014
3	Usage of Equipments	The purchaser would supply the equipments in Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), PEC Campus, Pillaichavady, Puducherry-605014.
4	Scope of Tender	Design, Development and Supply of Customized Development Boards for Electronic Design & Fab LAB at AIC-PECF.
5	Specification / details	Detailed specifications are given in tender at Annexure-A
6	Website for details of tender	http://www.aicpecf.org The prospective bidders are advised to remain in touch with the website for any update in respect of this tender
7	Location(s) of supplies	Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), PEC Campus, Pillaichavady, Puducherry-605014
8	Earnest Money Deposit (EMD)	EMD is exempted for taking part in the tendering process.
9	Bank Guarantee	a) The selected bidder should submit a Bank Guarantee of 2.5% of the purchase order value for a period of 1 Year along with the deliverables <u>before the release of the 25% payment for the PCB – Stage III of the product specified by the purchaser.</u> The Bank Guarantee shall be released by AIC-PECF only after satisfactory performance of the procured items for a minimum period of one year. In the event of any non-compliance in the delivered items by the bidder, the entire bank guarantee shall be forfeited.
10	Non-Disclosure and Product Development Agreement	The selected bidder should execute a Non-Disclosure and Product Development agreement with AIC-PECF before the release of Purchase order.

11	Cost of Tender Documents	<p>The tender document can be downloaded from the following official website of the purchaser: www.aicpecf.org</p> <p>The tender document fee is Rs.500.00/- (Rupees Five Hundred only) to be paid in the form of demand draft in favour of “AIC-Pondicherry Engineering College Foundation” payable at Puducherry shall be enclosed with Technical Bid of the tender.</p>
12	Last date of submission of tender	Last date for the submission of tender is on 28.09.2020 at 4.30 hours by registered post.
13	Date of opening of Technical Bid (Envelope-1)	The technical bid of tenders will be opened at Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), Pondicherry Engineering College campus, Pillaichavady, Puducherry-605014 on 28.09.2020 at 3.00 PM.
14	Date of opening of Commercial Bid (Envelope-2)	The date for opening second envelope containing Commercial Bid will be intimated to the qualified bidders separately
15	Contact Address	<p>The Chief Executive Officer, Atal Incubation Centre-PEC Foundation (AIC-PECF), Pondicherry Engineering College campus, Department of EIE, Pillaichavady, Puducherry-605014. Email: ceo@aicpecf.org</p>

**Chief Executive Officer
AIC-PECF**

INSTRUCTIONS TO THE BIDDERS

INSTRUCTIONS TO THE BIDDERS

The Tender shall be submitted in accordance with these instructions, as under.

1. Abbreviations:

- a) Throughout this tender documents, the word / term:
- b) “AIM” means ATAL Innovation Mission.
- c) “day” means Calendar day
- d) “working day” means Monday to Friday in week
- e) “tender” means tender number **Proc/AIC-PECF/ 2020/036**
- f) “Material” means the equipment / accessories as detailed at Annexure(s).
- g) “EMD” means Earnest Money Deposit.
- h) “Purchaser” means Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF)
- i) “Bid” means the document and financial details submitted by bidder.
- j) “Bidder” means the eligible and qualified Original Equipment Manufacturers
- k) “Tenderer” means the eligible and qualified Original Equipment Manufacturers /
- l) “OEM” means Original Equipment Manufacturer
- m) “INR” means Indian Rupees.

2. Scope of Supplies:

- a) The material shall be supplied in compliance to the specifications mentioned in Annexure(A) of the tender.
- b) The specifications of the materials as mentioned in the Annexure(A) are the requirements of tender which should be matched exactly including the physical dimensions as per the following terms:
 - i. The materials should be custom designed as per the specifications given by AIC-PECF.
 - ii. The materials shall be manufactured as per the physical dimensions specified by AIC-PECF.

- iii. The printed circuit boards (PCB) top overlay of the boards should reflect the Brand name / logo / website of AIC-PECF and not the vendor.
- iv. The complete ownership of the product including the manufacturing and selling rights should be transferred to AIC-PECF. The vendor should produce a legal No objection certificate for the same and under no circumstances the bidder should claim the IP rights of the product.
- v. The Vendor should handover the following along with physical product:
 - Original Schematic File of the Product
 - Original PCB file of the Product
 - Bill of Materials in Original.
 - Original Gerber / Drill and other Manufacturing Files of the Product.
 - Technical documentation and Assembly guide.
 - No objection Certificate to AIC-PECF transferring the complete IP / Manufacturing rights of the Product.
 - Non-Disclosure and Product Development Agreement
 - Performance Bank Guarantee.

- c) After the supply of materials as mentioned in the Annexure(A), the bidder has to execute its installation & commissioning at the designated site in the location(s). No extra cost shall be paid for this reason.

- d) After the installation & commissioning , the training to the AIC-PECF personnel shall be given about the maintenance, information about Do's & Don'ts as well as trouble shooting & all other areas which are necessary for smooth functioning shall be provided at site, by the bidder. No extra cost shall be paid to the successful bidder for imparting this training.

- e) The bidder shall offer on-site comprehensive warranty of materials for **three years** from the date of successful commissioning at the designated location. The purchaser is not liable to pay any extra charges on any account during warranty period.

- f) The bidder shall support the purchaser in all respects for the smooth functioning of the installed materials / shifting from one place to another / dismantling of systems / reorientation requirements which may arise in future during the warranty period. The purchaser is not liable to pay any extra charges for the above said services.

3. Eligible Bidder:

- a) The intending Bidder, should be Original Equipment manufacturer (OEM) preferably located in the union territory of Puducherry or Chennai. The Bidder shall submit a self-declaration on their letter-head, along with the Technical Bid, confirming that they are original equipment manufacturers, regular in manufacturing and supplying similar equipment, as listed in this tender.
- b) The bidder should have the facility to service the equipment after the warranty period and should indicate the service centres available in Puducherry/Chennai.
- c) Startups recognized by government of India who have the design and manufacturing competencies of the items listed in annexure are eligible to participate in the bidding as per the government norms.

4. Location of supplies:

- a) The location where the equipment(s) are to be supplied through this tender is Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), PEC Campus, Pillaichavady, Puducherry-605014.
- b) The bidder is free to inspect the premises before submitting the bid under this tender.

5. Delivery

- a) The purchaser is interested for complete delivery of all materials listed in Annexure(s) by the bidder within thirty (30) calendar days from the date of issue of supply order. However, the bidder have an option to submit the best delivery time, but in any case the delivery should be before 45 days after the issue of supply order by purchaser.
- b) The material shall be inspected on receipt at site and bidder shall be responsible for any damage during the transit of machine/ equipment.
- c) The bidder shall not arrange part shipments and/or trans-shipments without the permission of purchaser. The insurance cover including insuring the goods against the loss or damage incidental to manufacture or acquisition, transportation, storage and delivery/Installation & Commissioning shall be obtained by the bidder in his own name and not in the name of purchaser. The purchaser will as soon as possible but not later than 20 days from the date of arrival of goods at destination shall notify the bidder of any loss or damage to the goods.

6. Warranty

- a) The bidder shall offer on-site comprehensive warranty of materials for **3 years** from the date of successful commissioning of materials at the designated location & shall cover each and every part of the system including parts having limited life etc. The purchaser is not liable to pay any extra charges on any account during warranty period.
- b) The bidder shall pay to the purchaser such compensations that may arise by reasons of the warranty therein contained but not attended by the bidder.
- c) Any part or parts fail or proved defective within the on-site warranty period specified above, owing to defect in design, material or workmanship, the bidder shall have to replace them at the place of installation without asking for any charges.
- d) During the warranty period, expert(s) shall be deputed at site by the bidder within two working days from the date of request from purchaser, to rectify and fixing the defects of materials at the location where equipment supplied. The cost of deputation of expert(s) and any other associated expenditure shall be borne by the bidder.

7. Maintenance Contract

The bidder shall cover the materials under Maintenance Contract for **two years** after the expiry of warranty period with actual financial charges from purchaser.

8. After Sales Services

- a) The bidder shall ensure to render after sales services during the warranty period and in the period of Maintenance Contract to the satisfaction of purchaser.
- b) The bidder will depute their service personnel within two working days to attend the service call received in writing from purchaser.

9. Manuals:

The bidder to supply two (2) sets of Installation, Operation, Maintenance and Training manuals in hard format and one (1) soft format along with installation.

10. Tender documents:

- a) The tender document can be downloaded from our website **www.aicpecf.org**
- b) The tender document fee is Rs.500.00/- (Rupees Five Hundred only) to be paid in the form of demand draft in favor of “**AIC-Pondicherry Engineering College Foundation**” payable at Puducherry shall be enclosed with Technical Bid of the tender.
- c) At any time prior to the deadline for submission of bids, the Purchaser may amend the Bidding Documents by issuing addendum. The prospective bidders are advised to remain in touch with the Website for any update in respect of this tender.

11. Authorization for submission of tender:

- a) The original and all copies of the bid shall be signed by a person duly authorized to sign on behalf of the Bidder. The written confirmation of authorization (in form of letter on the bidder's letter head) to sign on behalf of the bidder confirming the signature as a person duly authorized to sign should be attached with the technical bid of the tender.
- b) The person signing the tender form or any other documents on behalf of the Bidder shall be deemed to warrant that he has authority to bind the Bidder. If subsequently comes to light that the person so signed had no authority to do so, the purchaser may without prejudice to any other civil & criminal remedies cancel the tender and hold the Bidder liable for all costs, charges and damages.

12. Transfer of IP/Manufacturing Rights:

- a) The bidder should transfer the IP/Manufacturing Rights of the product to the purchaser through a separate agreement.
- b) Under no circumstances the bidder should claim any IP ownership of the product in future.

13) Submission of Tender:

- a) The bidder to examine all instructions, forms, terms and specifications in the tender documents and to furnish with its bid all documents or information as required by bidding document.
- b) The language for all the correspondence and documents related to the tender shall be in English / Tamil only. Moreover, the printed literature / technical details for the equipments shall also be in English/ Tamil.
- c) The tender must be placed in a properly sealed bidder envelope and addressed to

**The Chief Executive Officer,
Atal Incubation Centre-PEC Foundation,
Pondicherry Engineering College Campus,
Pillaichavady, Puducherry-605014.**

and the said *Bidder envelope* shall contain two sealed envelopes containing Technical & Commercial bids. The bidder envelope must be super-scribed with tender name, tender inquiry number and its due date. The two sealed envelopes inside the bidder envelope must be super-scribed as:

Envelope No-1: The said envelope is for technical bid & shall be super-scribed as **“Technical Bid”**

Envelope No-2: The said envelope is for commercial bid & shall be super-scribed as **“Commercial Bid”**.

d) If both or either of the envelopes are not sealed and marked as required, the Purchaser will assume no responsibility for the misplacement or premature opening of the bid.

e) All the columns of the tender shall be duly, properly and exhaustively filled in. Any corrections/over writing etc. in the tender must be signed by the person who is signing the tender.

f) Tenders received in open covers/ letters / fax / email will not be considered.

14) Financial Bid Submission:

a) Bidder shall take into account all costs including unloading at the location of purchaser, installation etc. for giving delivery of material at site(s) as detailed at Para 3 of Instructions to Tenderers before quoting the rates. In this regard no claim what so ever shall be entertained.

b) The price, only in Indian rupees, quoted in financial bid shall be firm and shall include all applicable taxes. Any variation in the taxes, duties, levies etc. till the commissioning of equipments to the location(s) shall be to the bidder's account. No extra payment shall be paid on account of any discrepancy in nomenclature of items. The Bidder shall seek clarifications if any before submitting the tender.

c) No representation for the enhancement of the prices of the accepted tender or alteration of the terms and conditions will be entertained till supplies are completed to the designated location(s).

15) Last date of submission of Tender:

- a) Last date for the submission of tender is on **28.09.2020** at 4.30 hours.
- b) The purchaser may, at its discretion, extend the deadline for the submission of bids by amending the Tender Documents, in which case all rights and obligations of the Purchaser and Bidders previously subject to the deadline shall thereafter be subject to the deadline as extended. The prospective bidders are advised to remain in touch with website for any update in respect of their tender.
- c) The purchaser shall not consider any bid that arrives after the deadline for submission of bids. Any bid received by the Purchaser after the deadline for submission of bids shall be declared late, rejected and returned unopened to the Bidder.

16) Opening of Technical Bid:

- a) The technical bid of tenders will be opened at Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), Pondicherry Engineering College campus, Pillaichavady, Puducherry-605014 on **29.09.2020** at 4.30 Hours.
- b) The Bidder or their authorized representative (one person only) may be present at the time of opening of the tender.

17) Opening of Commercial Bid:

- a) The Commercial Bid of only technically qualified bidders will be opened on the stipulated due date. The date & time for opening of Commercial Bid shall be intimated to the technically qualified bidders through email, after the evaluation of Technical Bid.
- b) Purchase reserves the right to accept or reject any or all the offer fully or partly without assigning any reasons and is not bound to accept the lowest bid since due weightage shall be given to several factors besides the financial bid.

18) Validity of tender:

- a) The tender shall be valid for a period of 45 days from the date of opening of the Technical Bid of tender. Terms and financial details submitted in the bid shall be treated as firm during the said period of 45 days.
- b) In exceptional circumstances, prior to the expiry of the bid validity period, the Purchaser may request bidders to extend the period of validity of their bids. The request and the responses shall be made in writing.

19) Evaluation of Bids:

- a) If there is a discrepancy between the unit price and the line item total that is obtained by multiplying the unit price by the quantity, the unit price shall prevail and the line item total shall be corrected, unless in the opinion of the Purchaser there is an obvious misplacement of the decimal point in the unit price, in which case the line item total as quoted shall govern and the unit price shall be corrected.
- b) If there is an error in a total corresponding to the addition or subtraction of sub totals, the subtotals shall prevail and the total shall be corrected; and
- c) If there is a discrepancy between words and figures, the amount in words shall prevail, unless the amount expressed in words is related to an arithmetic error, in which case the amount in figures shall prevail subject to (a) and (b) above.
- d) To assist in the examination, evaluation, comparison of the bids and qualification of the Bidders, the Purchaser may, at its discretion, ask any Bidder for a clarification of its Bid. Any clarification submitted by a Bidder in respect to its Bid and that is not in response to a request by the Purchaser shall not be considered. The Purchaser's request for clarification and the response shall be in writing only.
- e) If a Bidder does not provide clarifications of its bid by the date and time set in the Purchaser's request for clarification, its bid may be rejected.
- f) The Purchaser reserves the right to accept or reject any bid, and to annul the bidding process and reject all bids at any time prior to supply order, without thereby incurring any liability to Bidders.
- g) At the time the Contract is awarded, the Purchaser may increase or decrease the Quantity of equipments without any change in the unit prices or other terms & conditions of the bid and the Bidding Documents subject to the acceptance of bidder in writing for the same. The Purchaser reserves its right to split the offer based on the evaluation report and award contract accordingly.
- h) The purchaser have right to verify the particulars furnished by the bidder independently.

20) Bank Guarantee:

The selected bidder should submit a **Bank Guarantee** of **2.5%** of the purchase order value along with all deliverables before the release of the 25% payment for the PCB – Stage III of the product specified by the purchaser. The bank guarantee shall be released by AIC-PECF only after satisfactory performance of the procured items for a minimum period of **one Year**. In the event of any non-compliance in the delivered items by the bidder, the entire security deposit shall be forfeited.

21) Non-Disclosure & Product Development Agreement :

The selected bidder should maintain the confidentiality and secrecy of the data furnished by AIC-PECF. The selected bidder execute a Non-Disclosure and Product Development agreement with AIC-PECF before the release of Purchase order.

22) Notification of award:

- a) Prior to the expiry of the period of bid validity, the purchaser shall notify the successful Bidder, in writing, that its Bid has been accepted.
- b) The notification letter shall specify the sum that the Purchaser will pay to the bidder in consideration of the supply of materials with the details of selected equipment.

23) Packing:

- a) The bidder shall provide packing of the machine/ equipment, as is required to prevent their damages or deterioration during the transit to their final destination. The packing shall be sufficient to withstand, without limitation, rough handling during transit. In case the consignment received with damaged packaging, the purchaser would not accept the delivery.
- b) The equipment shall be securely boxed, crated and protected from mechanical damage, moisture etc. suitable for both storage and transit according to the nature of the material and mode of transport. The bidder shall be responsible for any loss/ damage to material during transportation to the designated location.

24) Delivery Time:

- a) The bidder shall indicate the period within which the ordered quantity will be supplied. The bidder shall note that in case bidder fails to supply within the period of delivery indicated by the bidder in technical bid of this tender, penalty @ 1% of value of the order per week of delay would be levied subject to maximum 2 weeks. It means, the

bidder shall have the liability of delayed supply to the maximum of 2 weeks after expiry of scheduled delivery date.

b) After that the supply order shall be cancelled and bidder will be debarred from participation in any future tenders.

c) The successful Bidder shall, within a week from the date of receipt of communication of acceptance of quotes from purchaser shall intimate his acceptance of the order. The successful bidder shall complete supplies strictly as per the accepted delivery period.

25) Payment:

Stage I: The 25% payment of total bill will be made by the purchaser by crossed account payee cheque / RTGS / NEFT / PFMS for which the bidder shall deliver the complete design along with the schematics of the items specified by the purchaser.

Stage II: The 25% payment of total bill will be made by the purchaser by crossed account payee cheque / RTGS / NEFT / PFMS for which the bidder shall deliver the complete PCB design and the necessary manufacturing files along with original BOM of the product specified by the purchaser.

Stage III: The 25% payment of total bill will be made by the purchaser by crossed account payee cheque / RTGS / NEFT / PFMS for which the bidder shall deliver the PCB of the product specified by the purchaser along with Bank Guarantee.

Stage IV: The 25% payment of total bill will be made by the purchaser by crossed account payee cheque / RTGS / NEFT / PFMS for which the bidder shall send bills in duplicate (original + copy) after Supply, Installation, Commissioning of equipment, giving the reference number of the purchase order along with copies of delivery note & satisfactory report on the Installation of equipment(s), from designated authority. The details about the designated purchaser department who is authorized to take the delivery of equipment(s) shall be informed to the successful bidder through the supply order placed for the supply of equipment(s).

26) Causes of rejection of tender:

a) While submitting the tender, if any of the prescribed conditions are not fulfilled or are incomplete in any form, the tender is liable to be rejected.

b) If any Bidder stipulates any condition of his own, such conditional tender is liable to be rejected.

27) Claims:

- a) If the material supplied are found to be off size and shape different than those in the accepted offer and are of specifications lower than those stipulated in the accepted offer, the purchaser shall have right to totally reject the materials and/or to claim for compensation from bidder.
- b) The bidder shall reimburse to purchaser, the claim lodged in writing within 15 (fifteen) days of its demand. The bidder shall also compensate for losses, if any, sustained by purchaser due to defective packing and/or wrong marking of the machine/ equipment.
- c) The bidder shall be responsible for arranging the rejected machine/ equipment to be removed at his cost from purchaser premises.

28) Address for communication:

All the communication with respect to the tender shall be addressed to:

The Chief Executive Officer,
Atal Incubation Centre-PEC Foundation (AIC-PECF),
Pondicherry Engineering College Campus,
Pillaichavady, Puducherry-605014.

29) Force Majeure:

- a) In the event of any unforeseen circumstances directly interfering with the supply of goods/work/service arising during the execution of order such as war, hostilities, acts of the public enemy, civil commotion, sabotage, fires, floods, earthquakes, explosions, epidemics, quarantine restrictions, strikes, lockouts, or acts of God, the Bidder shall, within a week from the commencement thereof, notify the same in writing to the Purchaser with reasonable evidence thereof.
- b) Either party shall have the option to terminate the contract on expiry of 45 days of commencement of such force majeure by giving 14 days “notice to the other party in writing. In case of such termination, no damages shall be claimed by either party against the other.

30) Code of Ethics:

- a) The Purchaser as well as the Bidder shall observe the highest standard of ethics including laws against fraud and corruption in force in India namely “Prevention of Corruption Act 1988”, during the procurement or execution of such contracts.
- b) If the bidders are found in Bid pooling or against law against fraud and corruption then their firms may be blacklisted.

31) Jurisdiction:

In the event of any dispute the legal matter shall be subjected to the jurisdiction of Puducherry Courts only.

32) Others

a) For any specific imported items the OEM should have an authorization certificate from the original supplier and should enclose a copy of the same with the Technical bid.

b) The bidder should have sufficient manpower / team size to execute the project and should not outsource the same to any other party/agency.

Declaration:

I/We confirm with our acceptance to the instructions (S.No-1 to 32 above) as given above.

DATE : **BIDDER’S SIGNATURE WITH SEAL**

PLACE :

Name.....

Designation.....

Email Address.....

Phone (office.....)

Phone (Mobile).....

Note: These duly signed “Instructions to the Tenders” as under shall be attached with technical bid of the tender as a mark of acceptance of bidder and any tender not confirming the instructions as under is liable to be rejected.

ANNEXURE-A
DETAILS OF REQUIREMENTS AND SPECIFICATIONS

Details of Requirements

sl.no	Development Boards	Assembled Boards	Non Assembled PCBs	Quantity	Specification
1	FPGA Development Board	25	50	75	Annexure - I
2	ARM Embedded Development Board	25	50	75	Annexure - II
3	Liquid Crystal Display Interface Board 16X2	50	50	100	Annexure - III
4	Liquid Crystal Display Interface Board 20X4	50	50	100	Annexure - IV
5	Analog to Digital Converter Interface Board	50	50	100	Annexure - V
6	Digital to Analog Converter Interface Board	50	50	100	Annexure - VI
7	Relay Interface Board	50	50	100	Annexure - VII
8	DC Motor Interface Board	50	50	100	Annexure - VIII
9	Stepper Motor Interface Board	50	50	100	Annexure - IX
10	GSM Modem Interface Board	50	50	100	Annexure - X
11	Zigbee Interface Board	50	50	100	Annexure - XI
12	Bluetooth Interface Board	50	50	100	Annexure - XII
13	RFID Interface Board	50	50	100	Annexure - XIII
14	InfraRed Sensor Interface Board	50	50	100	Annexure - XIV

15	Gas Sensor Interface Board	50	50	100	Annexure - XV
16	All in one Interface Board	50	50	100	Annexure - XVI
17	Customized Arduino Board	50	50	100	Annexure - XVII
18	Micro SD Card Board	50	50	100	Annexure - XVIII
19	IOT Trainer Board	50	50	100	Annexure - XIX
20	WIFI Interface Board	50	50	100	Annexure – XX
21	Graphical LCD Interface Board	50	50	100	Annexure – XXI
22	MCS51 Development Board	50	50	100	Annexure – XXII
23	Power Boards	50	50	100	Annexure – XXIII
24	Ribbon Type Interface Cables	-	-	3000	Annexure – XXIV
25	Raspberry PI 4 Model B Board	10	-	10	Annexure – XXV

ANNEXURE – I

FPGA Development Board

Dimensions: 12 x 12 cm

Number of 2 Pin RMC Male Connectors: 7

Number of 8 Pin RMC Male Connectors: 7

Specifications:

- Processor: Xilinx XC6SLX9 FPGA core processor
- 3,840 logic elements
- Four 18K-bit block RAM(72K bits)
- Four 18x18 pipelined hardware multipliers.
- Two clock DCMs.
- 24 mhz crystal clock frequency(max 300mhz)
- Operating temperature range is 0o c ~ 85o c.
- Speed grade is -4.
- Built-in LEDs for port output debugging
- Output Headers provide access to all port pins for easy interfacing to external devices
- Target XILINX FPGA XC6SLX9 is supplied with kit.
- On-Board RS232 Port for direct connection to PC's Serial Port
- On-Board Voltage regulators +5v +3.3v & +12v
- .Bit file for FPGA and .mcs file for PROM can be downloaded easily with the help of a user-friendly XILINX ISE Software
- The board supports on board JTAG for programming via the board's parallel port.
- All the I/O ports are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – II

ARM Embedded Development Board

Dimensions: 10x10 cm

Number of 2 Pin RMC Male Connectors: 6

Number of 8 Pin RMC Male Connectors: 6

Specifications:

- 32-bit ARM7 microcontroller in a tiny LQFP64 package.
- On-chip Flash Program Memory with In-System Programming.
- Minimum 45 general purpose I/O pins.
- 512KB programmable flash & 40KB data memory
- Low power real-time clock RTC
- Full-duplex enhanced two UART
- Two Fast I2C-buses with speed of 400 kb/s.
- One Serial Peripheral Interface
- Minimum 22 interrupt Sources
- Built in 10-bit high-speed parallel type ADC Interface.
- Single 10 bit DAC
- Two 32 bit timer
- Each timer have four capture and four compare channels
- Six PWM outputs pins.
- single switch for Toggling between programming/execution modes
- Target embedded microcontroller LPC2148 is supplied with kit.
- On-Board RS232 Port for direct connection to PC's Serial Port
- Minimum 8 LED for debugging output.
- All the I/O ports are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – III

Liquid Crystal Display Interface Board 16X2

Dimensions: 10x 6 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 3 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 1

Specifications:

- Maximum input voltage: 5.5VDC
- Operating input voltage: 5VDC
- 8-bit interface data bus
- Controller: HD47780 equivalent
- Character font size: 0.125"W x 0.200"H
- Display size: 2.5"L x 0.7"W
- Easy to Interface with any Development Board.
- On board provision for Contrast Adjustment.
- 8-bit LCD data bus and three control lines RS, R/W, EN are accessible via standard external headers for easy interfacing of external devices.
- Low power consumption.

ANNEXURE – IV

Liquid Crystal Display Interface Board 20X4

Dimensions: 15 X 15 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 3 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 1

Specifications:

- Maximum input voltage: 5.5VDC
- Operating input voltage: 5VDC
- 8-bit interface data bus
- Controller: HD47780 equivalent
- Character font size: 0.125"W x 0.200"H
- Display size: 5.7"L x 2.4"W
- Easy to Interface with any Development Board.
- On board provision for Contrast Adjustment.
- 8-bit LCD data bus and three control lines RS, R/W, EN are accessible via standard external headers for easy interfacing of external devices.
- Low power consumption.

ANNEXURE – V

Analog to Digital Converter Interface Board

Dimensions: 4.5 X 5.5 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 3 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 1

Specifications:

- Maximum Supply Voltage – 6.5V
- Analog Input Voltage Range – 0 to 5V
- Conversion Time = <100 μ s
- Temperature Range: 0 to 70C
- Resolution = 19.53mv
- 8-bit ADC module – PDIP
- On Board Clock frequency
- Jumper to choose External/ Internal Sensor Integration.
- Onboard Temperature Sensor (LM35) for easy troubleshooting
- Easy to Interface with any Development Board.
- Easily accessible Data and control Lines via Standard Connectors.

Specifications (LM35)

- Sensitivity - 10mv/c
- Accuracy – 0.5C
- Temperature Range - -55° to +150°C
- Supply Voltage - -0.2V to +35V
- Output Voltage -1V to +6V.

ANNEXURE – VI

Digital to Analog Converter Interface Board

Dimensions: 4.5 X 5.5 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 2

Specifications:

- Full scale error: ± 1 LSB
- Nonlinearity over temperature: $\pm 0.1\%$
- Full scale current drift: ± 10 ppm/ $^{\circ}\text{C}$
- High output compliance: -10V to +18V
- Wide power supply range: $\pm 4.5\text{V}$ to $\pm 18\text{V}$
- 8 Bit resolution
- Interface type - Parallel
- No Negative power supply required
- Typical settling time of 100nS
- Easy to Interface with any Development Board.
- Easily accessible Data and control Lines via Standard Connectors.

ANNEXURE – VII

Relay Interface Board

Dimensions: 8.5 X 7.5 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 4 Pin RMC Male Connectors: 1

Specifications:

- On Board 4-Relays with Current Amplifier Circuit
- Relay Contact Rating Amp - 15A
- Relay Coil Voltage - 12V DC
- Relay Output control up to 240V
- Onboard SPDT relays with switching capacity of 10A
- Output terminals are provided for direct interface of External Device.
- Can be interfaced with any microcontroller
- Robust and Reliable to Use.

ANNEXURE – VIII

DC Motor Interface Board

Dimensions: 6 X 5 cm

Number of 2 Pin RMC Male Connectors : 2

Number of 8 Pin RMC Male Connectors : 1

Specifications:

- On Board Driver Circuit
- Supply Voltage +12V(maximum Ratings)
- Logic supply Voltage +5V (maximum Ratings)
- Peak output Current Amp 1.2A
- Dual motor control.
- Easily integrated with any microcontroller-based system.
- All the I/O ports are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – IX

Stepper Motor Interface Board

Dimensions: 7.5 X 7 cm

Number of 2 Pin RMC Male Connectors : 2

Number of 8 Pin RMC Male Connectors : 1

Specifications:

- On Board Driver Circuit
- Operating Voltage – 5V DC
- Simple to use and Low-cost Board.
- Easily integrated with any microcontroller-based system.
- All the I/O ports are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – X

GSM Modem Interface Board

Dimensions: 5.5 X 5.5 cm

Number of 2 Pin RMC Male Connectors : 2

Specifications:

- Input Voltage: 5VDC
- LED for signal indication.
- TTL serial interface compatible with 3.3V and 5V MCU.
- Quad-band GSM 850, 900, 1800 and 1900MHz
- TCP/IP protocol stack support
- Accepts a standard SIM card
- Support standard extended open AT commands
- Send/receive SMS text messages
- GPRS class 10.
- Can be interfaced with any microcontroller Via UART.
- Standard external headers for easy interfacing of external devices.

ANNEXURE – XI

Zigbee Interface Board

Dimensions: 5 x 5 cm

Number of 2 Pin RMC Male Connectors: 2

Specifications:

-
- XBee/XBee-PRO ZB (S2C) XB24CZ7WIT-004
- 3.3V @ 120mA
- 2.7V-3.6V working voltage
- 250kbps Max data rate
- 63mW output (+17dBm)
- 1 mile (1600m) range
- 6 10-bit ADC input pins
- 8 digital IO pins
- 128-bit encryption
- Local or over-air configuration
- AT or API command set
- External Antenna Required.
- Transceiver - 100mtr Mesh network

XBEE RS232 Breakout Board

- Compatible for Xbee and Tarang series also.
- RS232 3.3volts 232 Converter based.
- Onboard regulated Power Supply - 12v DC input.

ANNEXURE – XII

Bluetooth Interface Board

Dimensions: 4 x 4 cm

Number of 2 Pin RMC Male Connectors: 2

Specifications:

- Bluetooth protocol: Bluetooth Specification v2.0+EDR
- Frequency: 2.4GHz ISM band
- Modulation: GFSK(Gaussian Frequency Shift Keying)
- Emission power: 4dBm, Class 2
- Sensitivity: -84dBm at 0.1% BER
- Speed: Asynchronous: 2.1Mbps(Max) / 160 kbps, Synchronous: 1Mbps/1Mbps
- Security: Authentication and encryption
- Profiles: Bluetooth serial port
- Power supply: +3.3VDC 50mA
- Working temperature: -20 ~ +75Centigrade

Bluetooth Breakout Board

- Compatible for HC05 & HC06 series also.
- UART Compatible
- Onboard regulated Power Supply - 12v DC input.

ANNEXURE – XIII

RFID Interface Board

Dimensions: 8.5 X6.5 cm

Number of 3 Pin RMC Male Connectors: 1

Number of 6 Pin RMC Male Connectors: 1

Specifications:

- Operating Frequency at 125khz
- Reading Range up to 100mm
- ASCII Output Format
- Internal Antenna
- Connects to Standard RS232 port of PC at 19200 baud
- On board Buzzer and LED indications
- Software support with straight forward user interface.
- All the I/O pins are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – XIV

IR SENSOR Interface Board

Dimensions: 7 x 7 cm

Number of 2 Pin RMC Male Connectors: 2

Specifications:

- On board IR Transmitter and Receiver.
- Provision for adjustable Receiver threshold
- Peak wavelength $\lambda_p=940\text{nm}$
- Continuous Forward Current IF 20 mA
- On board LED Indication.
- All the I/O pins are accessible via standard external headers for easy interfacing of external devices.

ANNEXURE – XV

GAS Sensor Interface Board

Dimensions: 5 X 5 cm

Number of 2 Pin RMC Male Connectors: 2

Specifications:

- Working voltage: DC 5V
- High Sensitivity to LPG, natural Gas, Town Gas & small sensitivity to smoke & alcohol
- Low Cost.
- Stable & Long Life.
- On board Power indication.
- Working Current: 150mA
- DOUT: TTL output
- AOUT: Analog output
- Preheat time: Over 20s

ANNEXURE – XVI

All-In-One Interface Board

Dimensions: 25 X 12 cm

Number of 2 Pin RMC Male Connectors: 16

Number of 8 Pin RMC Male Connectors: 13

Specifications:

- 8 LED interfacing board with 8-bit transceiver IC 74HC245
- On-board 16x2 LCD Interface.
- On-board 8 inputs switch Interface.
- Built in 8-bit high-speed DAC Interface with settling time of 100nS
- On-board 4x1 relays Interface with switching capacity of 10A
- Built in 8-bit high-speed parallel type ADC Interface.
- On-board temperature sensors LM35.
- Dual DC motor Interface.
- On-board stepper motor Interface.
- Built in 4x4 matrix keypad interface unit.
- On-Board buzzer Interface.

ANNEXURE – XVII

Customized Arduino Development Board

Dimensions: 8.5 x 7 cm

Number of 2 Pin RMC Male Connectors: 9

Number of 4 Pin RMC Male Connectors: 1

Number of 6 Pin RMC Male Connectors: 1

Number of 16 Pin RMC Male Connectors: 1

Specifications:

- Microcontroller : ATmega328
- Operating Voltage : 5V
- Input Voltage (recommended) : 7-12V
- Digital I/O Pins : 14 (of which 6 provide PWM output)
- Analog Input Pins : 6
- DC Current per I/O Pin : 40 mA
- Flash Memory : 32 KB (ATmega328)
of which 0.5 KB used by bootloader
- SRAM : 2 KB (ATmega328)
- EEPROM : 1 KB (ATmega328)
- Clock Speed : 16 MHz
- Easy programming of the flash memory with a USB Port of a computer.
- On board power regulator and power on LED.
- Built in 12V, 5V and 3.3V Power supply Unit for interfacing external devices.
- On Board LED and Switches for Debugging I/O functions.
- On Board analog sensor(Preferably LM35 / Trim Pot)
- Output Headers provide access to all port pins for easy interfacing to external devices.

ANNEXURE – XVIII

Micro SD Card Interface Board

Dimensions: 4.5 x 4.5 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 1

Specifications:

- Supports FAT file system SD carrier
- SPI Interface
- Support Micro SD Card, Micro SDHC card
- Output Headers provides access for easy interfacing to external devices.
- Operating voltage: 5V
- On board 3.3V conversion for SD Card.

ANNEXURE – XIX

IoT Development Board

Dimensions: 11 X 10 cm

Number of 2 Pin RMC Male Connectors: 4

Number of 4 Pin RMC Male Connectors: 1

Number of 6 Pin RMC Male Connectors: 1

Specifications:

- Processor: ATmega328pu
- Arduino Compatible Board
- On-board LED debugging output.
- On-board 16x2 LCD Interface.
- On-board switch Interface.
- On-board Analog Sensor LM35, LDR & Trim POT.
- On board integrated wifi module: ESP8266
- Easy programming of the flash memory with a USB Port of a computer.
- Built-in Flash: 32Mbit
- WiFi protocol: IEEE 802.11 b/g/n
- Built in 5V and 3.3V Power supply Unit for interfacing external devices.
- Power on LED indication.

ANNEXURE – XX

WIFI Interface Board

Dimensions: 5 x 5 cm

Number of 2 Pin RMC Male Connectors: 2

Specifications

- 802.11 b/g/n
- Module : ESP8266
- Wi-Fi Direct (P2P), soft-AP
- Integrated TCP/IP protocol stack
- Integrated TR switch, balun, LNA, power amplifier and matching network
- Integrated PLLs, regulators, DCXO and power management units
- +19.5dBm output power in 802.11b mode
- Power down leakage current of <10uA
- 1MB Flash Memory
- Dimensions: 25 x 15 x 11 mm (LxWxH)
- PCB Thickness: 1mm
- SDIO 1.1 / 2.0, SPI, UART
- STBC, 1×1 MIMO, 2×1 MIMO
- A-MPDU & A-MSDU aggregation & 0.4ms guard interval
- Wake up and transmit packets in < 2ms
- Standby power consumption of < 1.0mW (DTIM3)
- Breakout board for ESP8266
- Output Headers provide access to all port pins for easy interfacing to external devices.

ANNEXURE – XXI

Graphical LCD Interface Board

Dimensions: 15 x 10 cm

Number of 2 Pin RMC Male Connectors: 1

Number of 8 Pin RMC Male Connectors: 2

Specifications

- Graphical Display Pixel : 128 X 64
- Built-in Controller
- Maximum input voltage: 5.5VDC
- Operating input voltage: 5VDC
- 8-bit interface data bus
- Built-in Backlight
- Overall: 78.0x70.0x13.0mm
- Viewable Area: 62.0x44.0 mm
- Output Headers provide access to all pins for easy interfacing to external devices.

ANNEXURE – XXII

MCS51 Development Board

Dimensions: 7.5 X 8 cm

Number of 2 Pin RMC Male Connectors: 4

Number of 8 Pin RMC Male Connectors: 6

Specifications

- Microcontroller : nuvoton W78E052DDG
- Core Architecture : 8052
- Max Operating Temperature: 85 °C
- Memory Size (ROM) : 8 kB
- Memory size (RAM) : 256 bytes
- Min Operating Temperature: -40 °C
- Number of I/Os : 32
- Oscillator Type : External
- The board is in system Programmable via the board's USB port eliminating the need for separate device programmer.
- On Board Power Supply Unit for easily interface with other External Boards.
- On board LEDs & Switches.
- Output Headers provide access to all port pins for easy interfacing to external device.
- Target Embedded microcontroller Nuvoton w78E052DDG is supplied with kit.
- Windows XP/7/8/10 Compatible.

ANNEXURE – XXIII

Power Boards

Dimensions: 10 x10 cm

Number of 2 Pin RMC Male Connectors: 12 nos

Specifications

- Input Voltage: 7V-36V DC or 6 -27V AC
- Output Voltage : 12 DC & 5V DC & 3.3V DC With double or more expansion output pins.
- Output Current: Max. 1.2A
- On Board AC to DC Converter circuit.
- Output Headers provide access for easy interfacing to external devices.
- Stable and high efficiency DC-DC step-down power module.

ANNEXURE – XXIV

Ribbon Type Interface Cables

Cable Length: 20 cm

Specifications

Items	Quantity(no's)
8 Pin RMC Cable (Female to Female)	1000
2 PIN RMC Cable (Female to Female)	1000
4 PIN RMC Cable (Female to Female)	500
3 PIN RMC Cable (Female to Female)	500

ANNEXURE – XXV

Raspberry PI 4 Model B Board

Dimensions: 8.5 x 5.6 cm

Specifications

- Broadcom BCM2711, Quad core Cortex-A72 (ARM v8) 64-bit SoC @ 1.5GHz
- 8GB LPDDR4-3200 SDRAM
- 2.4 GHz and 5.0 GHz IEEE 802.11ac wireless, Bluetooth 5.0, BLE
- Gigabit Ethernet
- 2 USB 3.0 ports; 2 USB 2.0 ports.
- Raspberry Pi standard 40 pin GPIO header (fully backwards compatible with previous boards)
- 2 × micro-HDMI ports (up to 4kp60 supported)
- 2-lane MIPI DSI display port
- 2-lane MIPI CSI camera port
- 4-pole stereo audio and composite video port
- H.265 (4kp60 decode), H264 (1080p60 decode, 1080p30 encode)
- OpenGL ES 3.0 graphics
- Micro-SD card slot for loading operating system and data storage
- 5V DC via USB-C connector (minimum 3A*)
- 5V DC via GPIO header (minimum 3A*)
- Power over Ethernet (PoE) enabled (requires separate PoE HAT)
- Operating temperature: 0 – 50 degrees C ambient

ANNEXURE -B

UNDERTAKING FROM BIDDER ON THEIR LETTER HEAD.

(In the official Letter Head of the Bidder)

To

The Chief Executive Officer (CEO)
Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF),
Pondicherry Engineering College Campus,
Pillaichavady, Puducherry-605014.

Dear Sir,

Subject: Undertaking for the participation to the tender No.....due
for opening of technical bid on.....

HAVING EXAMINED AND PERUSED THE FOLLOWING DOCUMENTS

1. Notice Inviting Tender
2. Instruction to the Bidders
3. Specifications of Equipments to be supplied and installed (Annexure-A)
4. Technical Bid (Annexure-C)
5. Commercial Bid (Annexure-D)

I/Wedo hereby submit the above tender in prescribed formats duly completed in all respects in accordance with the conditions applicable. If this tender is accepted, I/We agree to abide by and fulfill all the terms and conditions in the tender documents

I/We hereby distinctly and expressly declare and acknowledge that before the submission of this tender, I/We have carefully followed the instructions and I/We have understood the existing system of supply at the location(s) of purchaser including the scope and nature of duties expected from the Bidder.

I/We distinctly agree that I/We would hereafter make no claim or demand upon the purchaser based upon or arising out of any alleged misunderstanding or misconceptions or mistake on my/our part of the said stipulations, restrictions and conditions.

I/ We declare that our unit has never made any default in supplying the machine/ equipment to Government / Semi Government/ Central or State Public sector enterprise(s) in terms of quality and financial agreed supply conditions.

Any notice required to be served on me/us shall be sufficiently served on me/us by post(registered or ordinary) or courier or left at my/our address furnished herein.

.....
.....
.....

I/We fully understand the terms and conditions in the tender documents.

I/We understood that the purchaser is not bound to accept any proposal that it may receive without assigning any reason.

Dated this.....day of.....20...

Place :

Authorized Signatory

Seal:

ANNEXURE -C

**FORMAT & REQUIREMENTS FOR SUBMITTING TECHNICAL
BID**

6. ~~EMD payment details : Details of DD/RTGS/NEFT by which EMD paid~~

.....

7. PAN Number of bidder (self-attested copy to be enclosed):

.....

8. GST registration number of bidder(Self-attested copy to be enclosed):

.....

9. Delivery period after receipt of supply order from purchaser: (The purchaser interested for complete delivery of equipment by the bidder within thirty (30) calendar days from the date of issue of supply order. However, the bidder have an option to submit the best delivery time, but in any case the delivery should be before 45 days after the issue of supply order by purchaser.

Number of days (Calendar Days In figure)... (Calendar Days in words) for delivery from the date of issue of supply order by purchaser.

10. Details of address with contact details from where the bidder planned to offer after Sales Services during the Warranty & maintenance period :

.....

.....

.....

11. Details of address with contact details for at least three purchaser to whom the bidder supplied similar equipment in the last five (5) years and equipment shall be in operations to the satisfaction of buyer for the last three (3) years: The format for submission of details for at least three purchaser are as under: (the bidder can furnish details of even more than three purchaser)

a. Address of Purchaser with contact details (email and phone no.):

.....

.....

.....

b. Details of order for supply placed to bidder:

.....
.....
.....

c. Description and quantity of ordered equipment:

.....
.....
.....

d. Value of order in rupees:

.....
.....
.....

e. Date of completion of Delivery

.....
.....
.....

(The purchaser shall have liberty to contact any or all of purchaser to assess the performance of equipment supplied by bidder)

12. Documents - Details to be enclosed with the Technical bid by bidder are as under:

a) The bidder should be Original Indian Equipment manufacturers, the bidder should submit a self-declaration on their letter-head, confirming that they are regular in manufacturing & supplying the similar equipments, as asked in this tender, for the last Three (3) years. The bidder should submit the copy of the certificate of incorporation / registration certificate along with copy of Income tax filing for the past three financial years.

b) Undertaking as per annexure-B on official Letter Head

- c) Duly signed all pages “Instructions to Tenderers” of the tender document as a mark of acceptance.
- d) The letters substantiating performance from at least three (03) other purchasers, to whom, the similar equipment supplied by the bidder in last five (05) years, wherein, the equipment shall be in operation to the satisfaction of buyer for the last three (03) years, to access performance of the equipment supplied by your organization.
- e) Technical Literature of equipment(s) with particular reference to the modal of equipment proposed to supply against this tender along with reference of website to assess the further features.
- f) Authorization letter in favour of personnel to sign the tender behalf of bidder.
- g) ~~Self-certified copy of valid certificate for claiming EMD exemption.~~
- h) ~~Self-certified copy of valid certificate for claiming Tender Fee exemption.~~
- i) Self-attested copy of valid GST registration.
- j) Self-attested copy of valid PAN number.
- k) The Bidders shall furnish complete Technical details of equipment/equipment/material for the equipment offered to supply through the participation of this tender (use separate sheet to elaborate the details of technical specifications such as Measuring Range/Size, Least Count/Resolution, Accuracy, Materials used, Accessories, Tools, Spares etc.)
- l) To submit all supporting information with respect to the technical data, drawings or booklets of product. Any product brief, test certificates available may be enclosed.

I / We as bidder certify that:

- a) The tender shall remain valid for acceptance for 45 days from the date of opening the Technical Bid of the tender.

- b) Agree to offer services for onsite comprehensive warranty on the equipment(s) supplied through this tender.
- c) Agree to offer services for maintenance contract for the next three years for the equipment(s) supplied through this tender.
- d) Agree to impart onsite training to the designated personnel of purchase for 3 working days
- e) No price of any Equipment/ Equipment/ Spares/ Accessories shall be given in Technical Bid.
- f) All above equipments should be provided with safety features/ curtains/enclosures/ etc. wherever applicable.
- g) Units should certify that all consumables, electrical and electronic parts of the product conform to national/ international standard(s).
- h) Name & Signature of the authorized bidder with stamp Contact details of authorized person of bidder who have signed the tender.

Name.....

Designation.....

Email Address.....

Phone (office).....

Phone (Mobile).....

ANNEXURE -D

**FORMAT & REQUIREMENTS FOR SUBMITTING COMMERCIAL
BID**

FORMAT FOR SUBMISSION OF COMMERCIAL BID

1. Tender Ref. No:
2. Name of the Bidder:
3. The financial offer to execute the supply as per the tender:

Supply, Installation, and Commissioning of _____ to Atal Incubation Centre-Pondicherry Engineering College Foundation (AIC-PECF), Pondicherry Engineering College Campus,Pillaichavady, Puducherry-605014.
and Offered financials for the above tender & training to authorized personnel of AIC-PECF with commitment to offer on site after sales Services in the period of Warranty and maintenance contract.

Sl Nr	Details of Materials / Equipments	Basic price for supply of single unit in INR (X)	Quantity to be supplied in number of units (Y)	Total basic price in INR (Multiply X & Y)
Total landed cost for the supply of total quantity at AIC-PECF, Pondicherry Engineering College Campus,Pillaichavady, Puducherry-605014. (In INR)				

The followings to be noted while submitting financial details for the supply of equipment:

- a) The bidder shall offer their competitive offer.
- b) The purchaser will not issue any form ('C' and 'D') towards rebate / exclusion of GST etc.
- c) The bidder will not be entitled to any increase in rate of taxes occurring during the period of delivery even if there is delay in supplies / completion attributed to him.
- d) The Total Cost quoted above should be inclusive of basic price, statutory levies and taxes, duties, Transportation, Incidental Services (including Insurance, Loading/ Unloading, Packing & Forwarding charges, etc.), Installation & Commissioning, Demonstration & Training, on-site warranty and maintenance contract.
- e) The price competitiveness shall be given due consideration while analyzing the Commercial Bid.

I / We as bidder certify that:

- a) The tender shall remain valid for acceptance for 45 days from the date of opening the Technical Bid of the tender.
- b) Agree to offer services for onsite comprehensive warranty on the equipments(s) supplied through this tender.
- c) Agree to offer services for maintenance contract for the next two years for the equipment(s) supplied through this tender after warranty.
- d) Agree to impart onsite training to designated personnel of purchase for 3 working days
- e) Agree to three (2) sets of the Installation, Operation, Maintenance, Training Manual with equipments.
- f) Agree that the offer price is valid for the period of 45 days from the date of opening of technical bid of this tender.

g) Further confirm that we agree with the terms and conditions specified in “Instructions to Bidders” and if selected, the execution of supplies would be made in compliance.

Signature of the authorized bidder with stamp:

Contact details of authorized person of bidder who have signed the tender.

Name	
Designation	
Email Address	
Phone Number (office)	
Mobile Number	
Registered Address	